

AMENDMENTS TO THE CLAIMS

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1. (Currently amended) A copper alloy suitable for an IC lead pin for a pin grid array provided on a plastic substrate, wherein the copper alloy is selected from the group consisting of:

a copper alloy consisting of 0.05 to 0.5 wt% of Zn and 0.05 to 0.5 wt% of Mg, with the balance being made of unavoidable impurities and Cu; and

a copper alloy consisting of 0.1 to 1.0 wt% of Sn, with the balance being made of unavoidable impurities and Cu; and

~~a copper alloy consisting of 0.1 to 1.0 wt% of Sn and 0.1 to 0.6 wt% of Ag, with the balance being made of unavoidable impurities and Cu;~~

wherein the copper alloy has conductivity of 50% IACS or more, and tensile stress of 400 MPa or more but 650 MPa or less.

2. (Previously presented) The copper alloy as claimed in claim 1, which is the copper alloy consisting of 0.05 to 0.5 wt% of Zn and 0.05 to 0.5 wt% of Mg, with the balance being made of unavoidable impurities and Cu.

3. (Previously presented) The copper alloy as claimed in claim 1, which is the copper alloy consisting of 0.1 to 1.0 wt% of Sn, with the balance being made of unavoidable impurities and Cu.

4. (Currently amended) ~~The copper alloy as claimed in claim 1, which is the copper alloy consisting of 0.1~~ A copper alloy suitable for an IC lead pin for a pin grid array provided on a plastic substrate, the copper alloy consisting of 0.7 to 1.0 wt% of Sn and 0.1 to 0.6 wt% of Ag, with the balance being made of unavoidable impurities and Cu

wherein the copper alloy has conductivity of 50% IACS or more, and tensile stress of 400 MPa or more but 650 MPa or less.

5. (Cancelled)

6. (Cancelled)

7. (Cancelled)